

THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Cheng-Lien Chiang
Assignee: Bridge Semiconductor Corporation
Title: SEMICONDUCTOR PACKAGE DEVICE THAT INCLUDES
AN INSULATIVE HOUSING WITH A PROTRUDING
PERIPHERAL PORTION
Serial No.: 10/655,819 Filed: September 5, 2003
Examiner: Unknown Group Art Unit: 2812
Atty. Docket No.: BDG005-1-4

COMMISSIONER FOR PATENTS
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Alexandria, VA 22313-1450

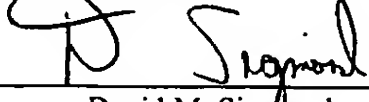
REQUEST FOR CORRECTED FILING RECEIPT

Attached is a copy of the official filing receipt received from the Patent and Trademark Office in the captioned-application for which a corrected filing receipt is respectfully requested.

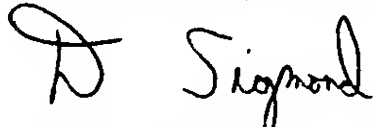
The Non-Publication Request should be "Yes" (rather than "No"). A Request for Nonpublication of Application was submitted with the captioned-application on filing. A copy of the Request is attached.

The correction is noted in red ink on the attached copy of the filing receipt.

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on December 4, 2003.


David M. Sigmond
Attorney for Applicant
12/4/03
Date of Signature

Respectfully submitted,


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UNITED STATES PATENT AND TRADEMARK OFFICE

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APPL NO.	FILING OR 371 (c) DATE	ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO	DRAWINGS	TOT CLMS	IND CLMS
10/655,819	09/05/2003	2812	861	BDG005-1-4	29	60	6

David M. Sigmond
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CONFIRMATION NO. 8002

FILING RECEIPT



OC000000011378582

Date Mailed: 12/01/2003

Receipt is acknowledged of this regular Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Filing Receipt Corrections, facsimile number 703-746-9195. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)

Cheng-Lien Chiang, Taipei, TAIWAN;

Assignment For Published Patent Application

Bridge Semiconductor Corporation;

Domestic Priority data as claimed by applicant

This application is a CON of 10/059,686 01/29/2002
 which is a CON of 10/042,812 01/09/2002

Foreign Applications

If Required, Foreign Filing License Granted: 11/28/2003

Projected Publication Date: 03/11/2004

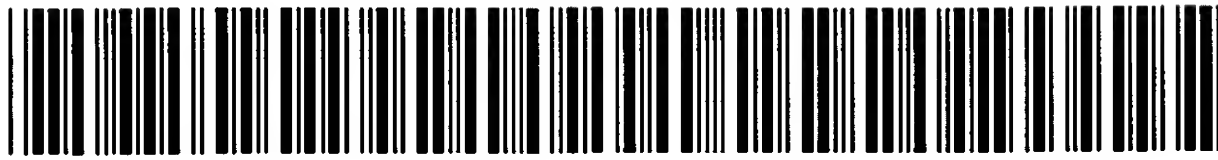
Non-Publication Request: ~~No~~ Yes

Early Publication Request: No

**** SMALL ENTITY ****

Title

Semiconductor package device that includes an insulative housing with a protruding peripheral portion



Creation date: 01-02-2004
Indexing Officer: ESHASH - EKRAM SHASH
Team: OIPEBackFileIndexing
Dossier: 10629640

Legal Date: 12-08-2003

No.	Doccode	Number of pages
1	OATH	7

Total number of pages: 7

Remarks:

Order of re-scan issued on